2SD2133

Silicon NPN epitaxial planar type

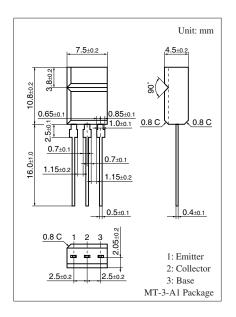
For low-frequency power amplification driver

■ Features

• Low collector-emitter saturation voltage V_{CE(sat)}

■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	60	V	
Collector-emitter voltage (Base open)	V _{CEO}	50	V	
Emitter-base voltage (Collector open)	V_{EBO}	5	V	
Collector current	I_C	1	A	
Peak collector current	I_{CP}	1.5	A	
Collector power dissipation	P _C	1.5	W	
Junction temperature	T_{j}	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 10 \mu\text{A}, I_E = 0$	60			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 2 \text{ mA}, I_B = 0$	50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \ \mu A, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 20 \text{ V}, I_{E} = 0$			0.1	μΑ
Forward current transfer ratio	h _{FE1} *1, 2	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}$	85		340	_
	h _{FE2} *1	$V_{CE} = 5 \text{ V}, I_{C} = 1 \text{ A}$	50	100		
	h _{FE3}	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ mA}$	35			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.2	0.4	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.85	1.20	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$ 200		200		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		11		pF
(Common base, input open circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

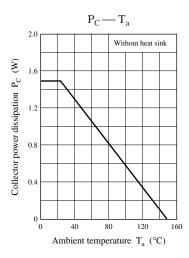
2. *1: Pulse measurement

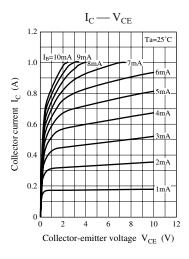
*2: Rank classification

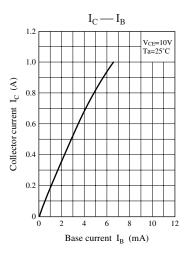
Rank	Q	R	S
h _{FE1}	85 to 170	120 to 240	170 to 340

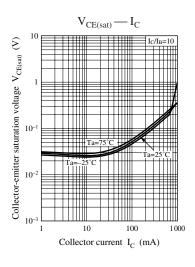
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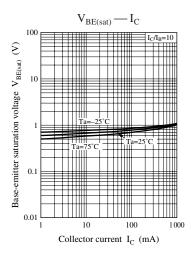
Panasonic

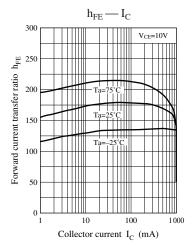


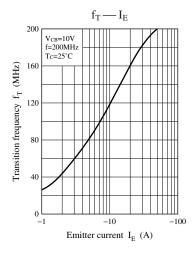


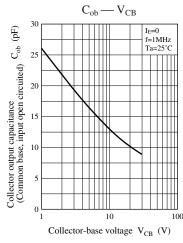


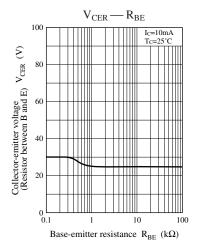




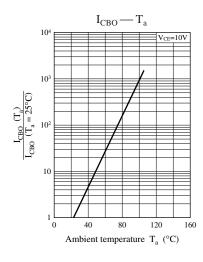


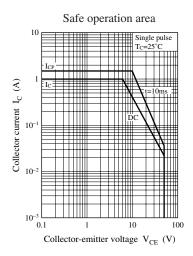


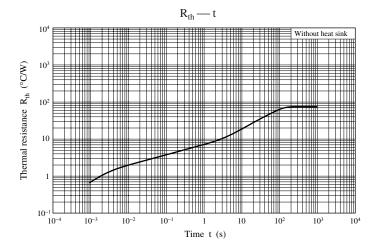




2 SJD00244BED







SJD00244BED 3

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